

MOUNTED CIRCUIT SUBSTRATE AND METHOD FOR FABRICATING
THE SAME FOR SURFACE LAYER PADS THAT CAN WITHSTAND
PAD EROSION BY MOLTEN SOLDER APPLIED OVER
A PLURALITY OF TIMES

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ABSTRACT OF THE DISCLOSURE

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A mounted circuit substrate has at least one
conductive layer. The side faces of a component mounting
pad is formed on a surface of the substrate, and includes
at least a columnar pattern made of a metal highly
15 resistant to erosion by solder. The side faces of the
component mounting pad are completely covered with an
organic insulating layer. Therefore, the component
mounting pad can withstand molten solder stresses
accompanying component replacement even when component
20 replacement is done many times.